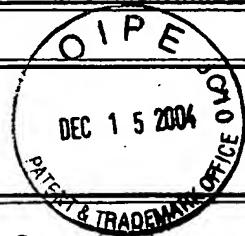


SUPPLEMENTAL APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0



Title of Invention	High Density Metal Capacitor Using Via Etch Stopping Layer as Field Dielectric in Dual-Damascence Interconnect Process	
Application Type:	regular, utility	
Attorney Docket Number:	1875.0230001/JDE	
Correspondence address:		
Customer Number:	26111	*26111*
Continuing Data:		
This is a Continuation of US application number 09/753,664, filed 2001-01-04.		
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